IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Thomas H. Ivers et al.

Serial No.: 09/231,618

Art Unit: 2823

Filed: January 14, 1999

Examiner: Collins, D.

For: Method for Improving

Adhesion to Copper

Atty Docket: FI9-98-172

SUBMISSION OF FORMAL DRAWINGS

Commissioner for Patents Washington, D.C. 20231

Sir:

Applicants submit herewith 1 sheet of formal drawings of Figs. 1-3.

Respectfully submitted,

Burton A. Amernick (24,852)

Pollock, Vande Sande & Amernick, R.L.L.P.

1990 M Street, N.W.

Washington, D.C. 20036-3425

Telephone: 202-331-7111

Date:

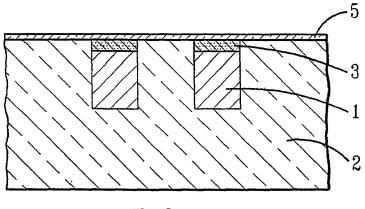
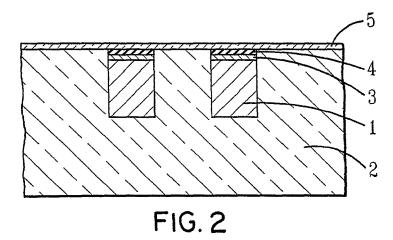


FIG. 1



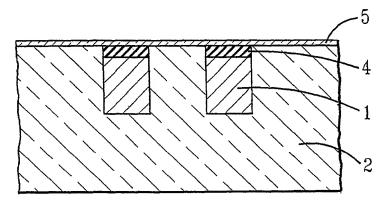


FIG.3